

Surface Mount Schottky Power Rectifier

POWERMITE® Power Surface Mount Package

MBRM2H100T3G, NRVBM2H100T3G

The Schottky Powermite[®] employs the Schottky Barrier principle with a barrier metal and epitaxial construction that produces optimal forward voltage drop-reverse current tradeoff. The advanced packaging techniques provide for a highly efficient micro miniature, space saving surface mount Rectifier. With its unique heatsink design, the Powermite[®] has the same thermal performance as the SMA while being 50% smaller in footprint area. Because of its small size, it is ideal for use in portable and battery powered products such as cellular and cordless phones, chargers, notebook computers, printers, PDAs and PCMCIA cards. Typical applications are AC–DC and DC–DC converters, reverse battery protection, and "ORing" of multiple supply voltages and any other application where performance and size are critical.

Features

- Low Profile Maximum Height of 1.1 mm
- Small Footprint Footprint Area of 8.45 mm²
- Low V_F Provides Higher Efficiency and Extends Battery Life
- Supplied in 12 mm Tape and Reel
- Low Thermal Resistance with Direct Thermal Path of Die on Exposed Cathode Heat Sink
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- This is a Pb-Free Device

Mechanical Characteristics:

- Powermite® is JEDEC Registered as D0-216AA
- · Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 16.3 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds

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SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES, 100 VOLTS



POWERMITE CASE 457

MARKING DIAGRAM



M = Date CodeB2H = Device Code= Pb-Free Package

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|---------------|------------------------|-------------------------|
| MBRM2H100T3G | Powermite (Pb-Free) | 12,000 / Tape & Reel |
| NRVBM2H100T3G | Powermite (Pb-Free) | 12,000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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MAXIMUM RATINGS

| Symbol | Rating | Value | Unit |
|--|---|-------------|------|
| V _{RRM} V _{RWM} V _R | Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | 100 | V |
| I _O | Average Rectified Forward Current (T _L = 160°C) | 2.0 | Α |
| I _{FSM} | Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | 50 | Α |
| T _{stg} , T _J | Storage and Operating Junction Temperature Range (Note 1) | -65 to +175 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

| Symbol | Characteristic | Value | Unit |
|-----------------|--|-------|------|
| Ψ_{JCL} | Thermal Resistance, Junction-to-Lead (Note 2) | 12 | °C/W |
| $R_{	heta JA}$ | Thermal Resistance, Junction-to-Ambient (Note 2) | | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient (Note 3) | | °C/W |

ELECTRICAL CHARACTERISTICS

| Symbol | Characteristic | Value | Unit |
|----------------|---|------------------------------|----------|
| V _F | Maximum Instantaneous Forward Voltage (Note 4) $ \begin{aligned} &(I_F = 1.0 \text{ A, } T_J = 25^{\circ}\text{C}) \\ &(I_F = 2.0 \text{ A, } T_J = 25^{\circ}\text{C}) \\ &(I_F = 1.0 \text{ A, } T_J = 125^{\circ}\text{C}) \\ &(I_F = 2.0 \text{ A, } T_J = 125^{\circ}\text{C}) \end{aligned} $ | 0.76 0.84 0.61 0.68 | V |
| I _R | Maximum Instantaneous Reverse Current (Note 4) (Rated dc Voltage, T _J = 25°C) (Rated dc Voltage, T _J = 125°C) | 20 1.0 | μA mA |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 2. Mounted with 700 mm² copper pad size (Approximately 1 in²) 1 oz FR4 Board.
- 3. Mounted with pad size approximately 20 mm² copper, 1 oz FR4 Board.
- 4. Pulse Test: Pulse Width ≤ 380 μs, Duty Cycle ≤ 2.0%.

^{1.} The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

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TYPICAL CHARACTERISTICS

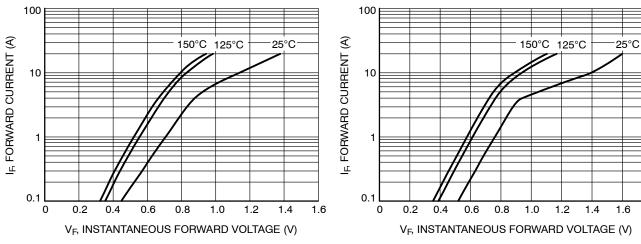


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

1.8

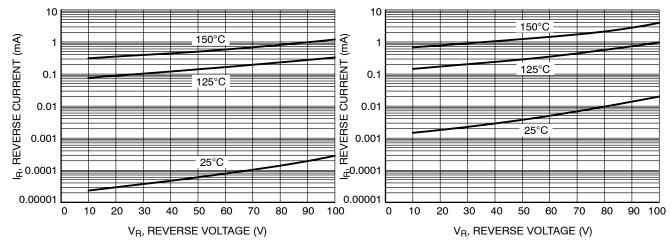


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

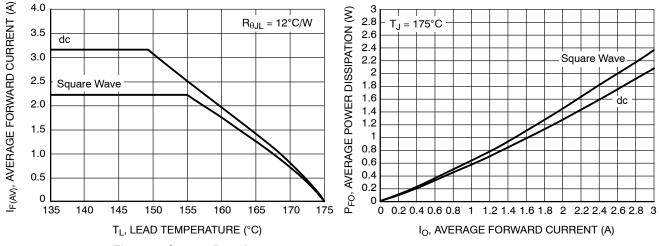


Figure 5. Current Derating

Figure 6. Forward Power Dissipation

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TYPICAL CHARACTERISTICS (continued)

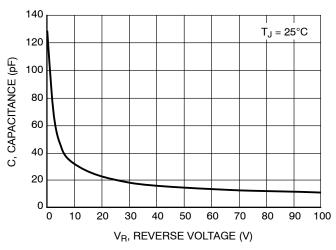


Figure 7. Capacitance

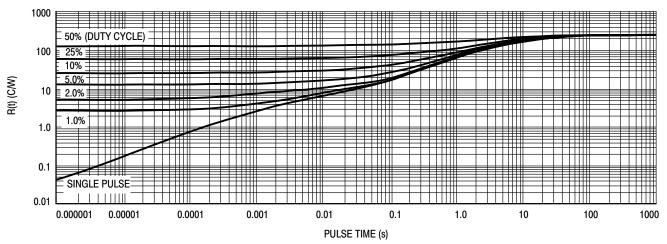


Figure 8. Thermal Response, Junction-to-Ambient (20 mm² pad)

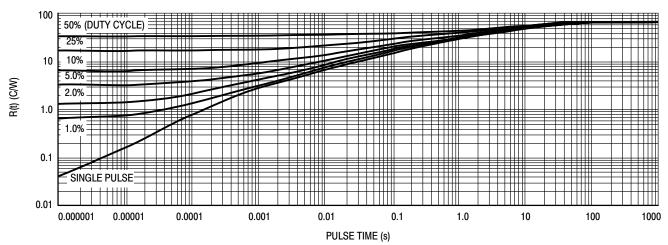


Figure 9. Thermal Response, Junction-to-Ambient (1 in² pad)

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h1

⊕ 0.08**M** C A B

PIN 1

PIN 2

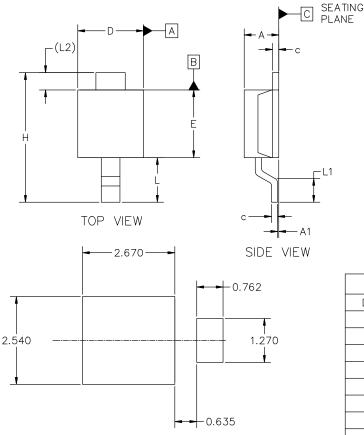




POWERMITE 1.90x1.96x1.00 **CASE 457**

ISSUE H

DATE 16 MAY 2025



⊕ 0.08**M** C A B BOTTOM VIEW **MILLIMETERS** DIM MIN NOM MAX0.85 Α 1.00 1.15 Α1 0.00 0.05 0.10 0.40 0.55 b 0.69 b1 0.70 0.85 1.00 С 0.10 0.18 0.25 D 1.75 1.90 2.05 Ε 1.75 1.96 2.18 Н 3.60 3.75 3.90 L 1.20 1.35 1.50

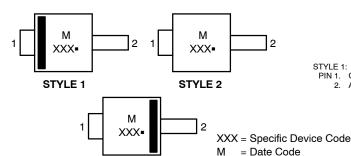
0.65

0.50 REF

RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb—Free Strategy and Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAMS*



STYLE 3

NOTES:

DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018. CONTROLLING DIMENSION: MILLIMETERS.

0.50

- DIMENSION D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

STYLE 1: PIN 1. CATHODE 2. ANODE PIN 1. ANODE OR CATHODE 2. CATHODE OR ANODE (BI-DIRECTIONAL)

STYLE 2:

L1

L2

STYLE 3: PIN 1. ANODE 2. CATHODE

0.80

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

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|------------------|--------------------------|---|-------------|
| DESCRIPTION: | POWERMITE 1.90x1.96x1.00 | | PAGE 1 OF 1 |

= Pb-Free Package

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